Thyristors

BT151X series C

GENERAL DESCRIPTION

Passivated thyristors in a full pack, Passivated thyristors in a full pack, plastic envelope, intended for use in applications requiring high bidirectional blocking voltage capability and high thermal cycling performance. Typical applications include motor control, industrial and domestic lighting, heating and static switching.

QUICK REFERENCE DATA

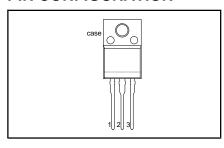
SYMBOL	PARAMETER	MAX.	MAX.	MAX.	UNIT
$egin{array}{c} V_{DRM}, \ V_{RRM} \ I_{T(AV)} \end{array}$	BT151X- Repetitive peak off-state voltages Average on-state current	500C 500 7.5	650C 650 7.5	800C 800 7.5	V A
I _{T(RMS)} I _{TSM}	RMS on-state current Non-repetitive peak on-state current	12 100	12 100	12 100	A A

PINNING - SOT186A

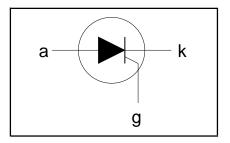
static switching.

PIN	DESCRIPTION
1	cathode
2	anode
3	gate
case	isolated

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.		MAX.		UNIT
V_{DRM}, V_{RRM}	Repetitive peak off-state voltages		-	-500C 500 ¹	-650C 650 ¹	-800C 800	V
I _{T(AV)} I _{T(RMS)} I _{TSM}	Average on-state current RMS on-state current Non-repetitive peak on-state current	half sine wave; $T_{hs} \le 69 ^{\circ}\text{C}$ all conduction angles half sine wave; $T_j = 25 ^{\circ}\text{C}$ prior to surge	-		7.5 12		A A
		t = 10 ms t = 8.3 ms	-		100 110		A A
l²t dl _⊤ /dt	I ² t for fusing Repetitive rate of rise of on-state current after triggering	t = 10 ms $I_{TM} = 20 \text{ A}; I_G = 50 \text{ mA};$ $dI_G/dt = 50 \text{ mA/}\mu\text{s}$	-		50 50		A²s A/μs
I _{GM} V _{RGM} P _{GM}	Peak gate current Peak reverse gate voltage Peak gate power		- - -		2 5 5		A V W
$\begin{array}{c} P_{G(AV)} \\ T_{stg} \\ T_j \end{array}$	Average gate power Storage temperature Junction temperature	over any 20 ms period	- -40 -		0.5 150 125		Ç Ç W

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¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15 A/µs.

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ISOLATION LIMITING VALUE & CHARACTERISTIC

 T_{hs} = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{isol}	R.M.S. isolation voltage from all three terminals to external heatsink	f = 50-60 Hz; sinusoidal waveform; R.H. ≤ 65%; clean and dustfree	ı	ı	2500	V
C _{isol}	Capacitance from pin 2 to external heatsink	f = 1 MHz	-	10	-	pF

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th j-hs}$ $R_{th j-a}$	Thermal resistance junction to heatsink Thermal resistance junction to ambient	with heatsink compound without heatsink compound in free air	1 1 1	- - 55	4.5 6.5 -	K/W K/W K/W

STATIC CHARACTERISTICS

 $T_j = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{GT}	Gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$	-	2	15	mΑ
I _L	Latching current	$V_{\rm D} = 12 \text{ V}; I_{\rm GT} = 0.1 \text{ A}$	-	10	40	mΑ
I _H	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	-	7	20	mΑ
ĺΫ́τ	On-state voltage	$I_{T} = 23 \text{ A}$	-	1.44	1.75	V
V _{GT}	Gate trigger voltage	$\dot{V}_{D} = 12 \text{ V}; I_{T} = 0.1 \text{ A}$	-	0.6	1.5	V
"		$V_{\rm D} = V_{\rm DRM(max)}$; $I_{\rm T} = 0.1 \text{ A}$; $T_{\rm i} = 125 ^{\circ}\text{C}$	0.25	0.4	-	V
I_D, I_R	Off-state leakage current	$V_D = V_{DRM(max)}^{Station}$; $V_R = V_{RRM(max)}$; $T_j = 125 ^{\circ}C$	-	0.1	0.5	mA

DYNAMIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV _D /dt	Critical rate of rise of off-state voltage	$V_{DM} = 67\% V_{DRM(max)}; T_j = 125 °C;$ exponential waveform Gate open circuit	50 200	130 1000	-	V/μs V/μs
t _{gt}	Gate controlled turn-on time	$I_{TM} = 40 \text{ A}; V_D = V_{DRM(max)}; I_G = 0.1 \text{ A}; $ $dI_G/dt = 5 \text{ A}/\mu\text{s}$	-	2	-	ν/μs μs
t _q	Circuit commutated turn-off time	$ \begin{array}{l} V_{D} = 67\% \ V_{DRM(max)}; \ T_{j} = 125 \ ^{\circ}C; \\ I_{TM} = 20 \ A; \ V_{R} = 25 \ V; \ dI_{TM}/dt = 30 \ A/\mu s; \\ dV_{D}/dt = 50 \ V/\mu s; \ R_{GK} = 100 \ \Omega \end{array} $	-	70	-	μs

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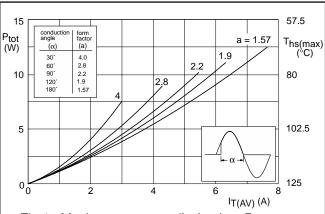


Fig.1. Maximum on-state dissipation, P_{tov} versus average on-state current, $I_{T(AV)}$, where $a = form \ factor = I_{T(RMS)} / I_{T(AV)}$.

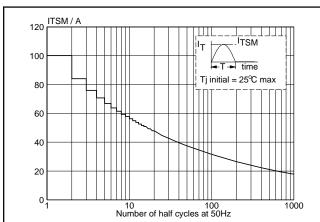


Fig.4. Maximum permissible non-repetitive peak on-state current I_{TSM}, versus number of cycles, for sinusoidal currents, f = 50 Hz.

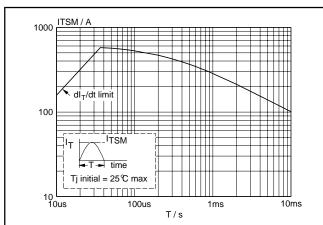


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \le 10$ ms.

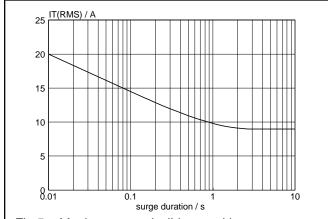


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{hs} \le 69$ °C.

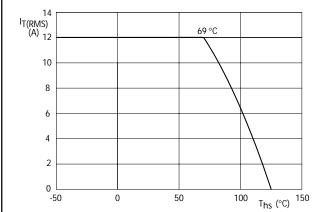
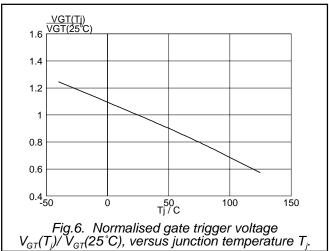
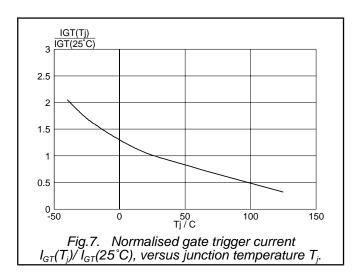


Fig.3. Maximum permissible rms current $I_{T(RMS)}$, versus heatsink temperature $T_{\rm hs}$.



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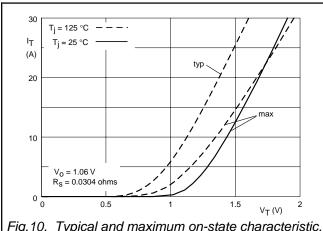


Fig. 10. Typical and maximum on-state characteristic.

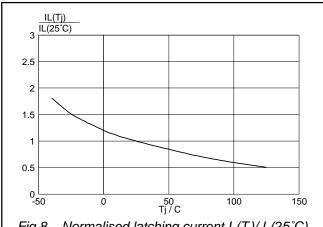


Fig.8. Normalised latching current $I_L(T_j)/I_L(25^{\circ}\text{C})$, versus junction temperature T_j .

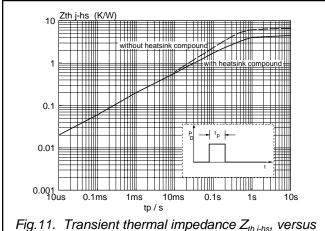


Fig.11. Transient thermal impedance $Z_{th i-hs}$, versus pulse width $t_{\rm p}$.

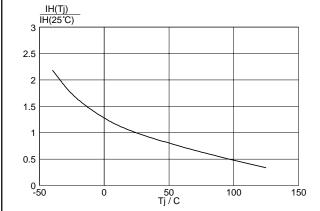


Fig.9. Normalised holding current $I_H(T_i)/I_H(25^{\circ}\text{C})$, versus junction temperature T_i .

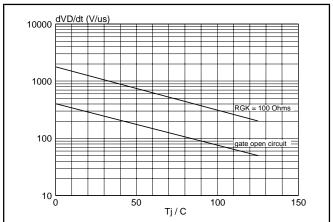
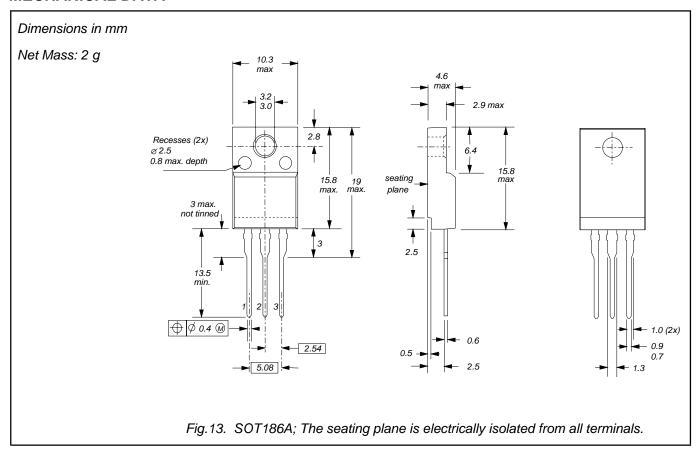


Fig.12. Typical, critical rate of rise of off-state voltage, dV_D/dt versus junction temperature $T_{j\cdot}$

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MECHANICAL DATA



- Notes
 1. Refer to mounting instructions for F-pack envelopes.
 2. Epoxy meets UL94 V0 at 1/8".

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DEFINITIONS

DATA SHEET STATUS					
PRODUCT STATUS ³	DEFINITIONS				
Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice				
Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product				
Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A				
	PRODUCT STATUS ³ Development Qualification				

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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² Please consult the most recently issued datasheet before initiating or completing a design.

³ The product status of the device(s) described in this datasheet may have changed since this datasheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.